# 2SB1574 (Tentative)

### Silicon PNP epitaxial planar type

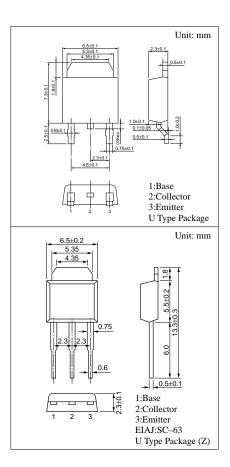
For low-frequency output amplification

#### Features

- Possible to solder radiation fin directly to printed cicuit boad
- Type with universal characteristics
- Collector breakdown voltage:  $V_{CBO}/V_{CEO} = -50V$
- Collector current:  $I_C = -2A$

#### Absolute Maximum Ratings $(T_C=25^{\circ}C)$

Parameter	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	-50	V
Collector to emitter voltage	$V_{CEO}$	-50	V
Emitter to base voltage	$V_{\rm EBO}$	-5	V
Peak collector current	$I_{CP}$	-3	A
Collector current	$I_{C}$	-2	A
Collector power dissipation (T <sub>C</sub> =25°C)	$P_{C}$	10	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C



#### ■ Electrical Characteristics (T<sub>C</sub>=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = -10V, I_E = 0$			- 0.1	μА
Collector to base voltage	V <sub>CBO</sub>	$I_{\rm C} = -10\mu A, I_{\rm E} = 0$	-50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{C} = -1mA, I_{B} = 0$	-50			V
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = -10\mu A, I_{\rm C} = 0$	-5			V
	h <sub>FE1</sub> *	$V_{CE} = -2V, I_{C} = -200 \text{mA}$	120		340	
Forward current transfer ratio	h <sub>FE2</sub>	$V_{CE} = -2V, I_{C} = -1A$	60			
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -1A, I_B = -50mA$		-0.2	- 0.3	V
Base to emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -1A, I_B = -50mA$		- 0.85	-1.2	V
Transition frequency	$f_T$	$V_{CB} = -10V$ , $I_E = 50mA$ , $f = 200MHz$		80		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10V, I_E = 0, f = 1MHz$		45	60	pF

#### \*h<sub>FE1</sub> Rank classification

Rank	R	S
h <sub>FE1</sub>	120 to 240	170 to 340

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